

IRFR5410

TO-252 P Channel MOS Field Effect Transistor
TO-252 P 沟道场效应管

1. Description 描述

This P Channel MOSFET encapsulated in a TO-252 Surface-Mounted Device (SMD) plastic package.

这种 P 沟道 MOS 场效应管采用 TO-252 表面贴装 (SMD) 塑料封装。

2. Features 特性

Feature 特性	Description 描述
Drain-Source Voltage 漏极-源极电压	$V_{DS} = -100V$
Drain Current(continuous) 漏极电流-连续	$I_D = -8.8A$
Applications 应用	<ul style="list-style-type: none">• Power Switch 电源开关• DC/DC Converters 直流/直流转换器
Environmental Compliance 环保合规	Totally Lead-Free & Fully RoHS Compliant. 完全无铅和符合 RoHS 标准 ^[1] Halogen and Antimony Free, "Green" Device. 无卤素和无镉, "绿色"器件 ^[2]
Automotive Compliance 汽车合规	Qualified according to AEC-Q101 and recommended for use in automotive applications. 通过了 AEC-Q101 认证, 推荐用于汽车电子应用场景。

[1] No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.

无铅, 完全符合欧盟标准 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) 和 2015/863/EU (RoHS 3)。

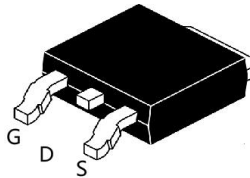
[2] Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

无卤素和无镉的“绿色”产品指溴含量<900ppm, 氯含量<900ppm (溴+氯总含量<1500ppm) 和镉化合物含量<1000ppm。

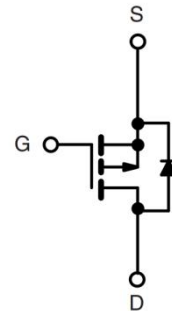


3. Mechanical Data 封装数据

Feature 特性	Description 描述
Package 封装	TO-252
Moisture Sensitivity Level 湿敏感度等级	J-STD-020 MSL1
Material 材料	Molded Plastic, “Green” Molding Compound; UL Flammability Classification Rating 94V-0. 模塑塑料封装, “绿色”成型复合材料; UL 可燃性等级 94V-0。
Dimensions 尺寸	2.286mm pitch; 6.1mm × 6.6mm × 2.3mm body 相邻引脚中心距为 2.286mm, 封装本体(不含引脚)尺寸为 6.1mm × 6.6mm × 2.3mm
Terminals Compliance 引脚合规	3 terminals, Tin Plated Leads; exposed die pad for good heat transfer; Solderable per MILSTD-202, Method 208 ^{e3} 3 个镀锡引脚, 外露散热焊盘以增强热传导; 可焊性符合 MIL-STD-202 标准中 208 方法 e3 条款的要求
Weight 重量	2.24 grams (Approximate) 约 2.24 克
Polarity 极性	See Diagrams Below 极性见下图



TO-252 Top View



Device Symbol

4. Ordering Information 订购信息

Part Number	Compliance	Package	Reel Size (inches)	Tape Width (mm)	Quantity Per Reel
IRFR5410	Automotive	TO-252	13	16	2500



5. Marking Information 丝印信息

Part Number	Marking Code
IRFR5410	FR5410

6. Absolute Maximum Ratings($T_a = +25^\circ\text{C}$) 绝对最大额定值

Characteristic 特性	Symbol 符号	Value 值	Unit 单位	
Drain-Source Voltage 漏极-源极电压	V_{DS}	-100	V	
Gate- Source Voltage 栅极-源极电压	V_{GS}	± 20	V	
Continuous Drain Current (continuous) 漏极电流-连续 ($T_j = 150^\circ\text{C}$)	$T_C = 25^\circ\text{C}$	I_D	-8.8	A
	$T_C = 70^\circ\text{C}$	I_D	-7.1	A
Continuous Source-Drain Current (Diode Conduction) 连续源漏极电流 (二极管导通状态)	I_S	-8.8	A	
Drain Current(pulsed)漏极电流-脉冲	I_{DM}	-25	A	

7. Thermal Characteristics($T_a = +25^\circ\text{C}$) 热特性

Characteristic 特性	Symbol 符号	Value 值	Unit 单位	
Power Dissipation 耗散功率 ^[3]	$T_C = 25^\circ\text{C}$	P_D	32.1 ^[4]	W
	$T_A = 25^\circ\text{C}$ ^[5]	P_D	2.5	W
Thermal Resistance From Junction To Ambient 结到环境的热阻	$R_{\theta JA}$	50	$^\circ\text{C}/\text{W}$	
Junction Temperature 结温	T_j	-55 ~ +150	$^\circ\text{C}$	
Storage Temperature 储藏温度	T_{stg}	-55 ~ +150	$^\circ\text{C}$	

[3] Duty cycle $\leq 1\%$. 占空比 $\leq 1\%$ 。

[4] See Safe Operating Area(SOA) curve for voltage derating. 电压降额请参见安全工作区(SOA)曲线。

[5] When Mounted on 1" square PCB (FR-4 material). 当安装在1英寸见方的FR-4材质PCB上时。



8. Electrical Characteristics($T_a = + 25^{\circ}\text{C}$) 电特性

Characteristic 特性	Symbol 符号	Min. 最小值	Typ. 典型值	Max. 最大值	Unit 单位	Conditions 条件
Drain-Source Breakdown Voltage 漏极-源极击穿电压	BV_{DSS}	-100	-	-	V	$I_D = -250\mu A,$ $V_{GS} = 0$
Gate Threshold Voltage 栅极开启电压	$V_{GS(th)}$	-1	-	-2.5	V	$I_D = -250\mu A,$ $V_{DS} = V_{GS}$
Zero Gate Voltage Drain Current 零栅压漏极电流	I_{DSS}	-	-	-1	μA	$V_{GS} = 0,$ $V_{DS} = -100V$
		-	-	-50	μA	$V_{GS} = 0,$ $V_{DS} = -100V$ $T_J = 125^{\circ}\text{C}$
		-	-	-250	μA	$V_{GS} = 0,$ $V_{DS} = -100V$ $T_J = 150^{\circ}\text{C}$
Gate Body Leakage 栅极漏电流	I_{GSS}	-	-	± 250	nA	$V_{GS} = \pm 20V,$ $V_{DS} = 0$
Static Drain-Source On-State Resistance 静态漏源导通电阻 ^[6]	$R_{DS(on)}$	-	0.25	-	Ω	$I_D = -3.6A,$ $V_{GS} = -10V$
		-	0.28	-	Ω	$I_D = -3.4A,$ $V_{GS} = -4.5V$
Diode Forward Voltage Drop 内附二极管正向压降 ^[6]	V_{SD}	-	-0.8	-1.5	V	$I_S = -2.9A,$ $V_{GS} = 0$
Input Capacitance 输入电容	C_{ISS}	-	1055	-	pF	$V_{GS} = 0,$ $V_{DS} = -50V,$ $f = 1MHz$
Common Source Output Capacitance 共源输出电容	C_{OSS}	-	65	-	pF	
Reverse Transfer Capacitance 反馈电容	C_{RSS}	-	41	-	pF	
Total Gate Charge 栅极电荷密度	Q_g	-	23.2	34.8	nC	$V_{GS} = -10V,$ $V_{DS} = -50V,$ $I_D = -3.6A$
		-	11.7	17.6	nC	$V_{GS} = -4.5V,$ $V_{DS} = -50V,$ $I_D = -3.6A$
Gate Source Charge 栅源电荷密度	Q_{gs}	-	3.5	-	nC	$V_{GS} = -4.5V,$ $V_{DS} = -50V,$ $I_D = -3.6A$
Gate Drain Charge 栅漏电荷密度	Q_{gd}	-	4.8	-	nC	
Gate Resistance 栅极电阻	R_g	1.2	5.7	11.5	Ω	$f = 1MHz$



Product DataSheet

Characteristic 特性	Symbol 符号	Min. 最小值	Typ. 典型值	Max. 最大值	Unit 单位	Conditions 条件
Turn-ON Delay Time 开启延迟时间	$t_{d(on)}$	-	7	14	ns	$V_{DD} = -50V,$ $R_L = 17.2\Omega$ $I_D \cong -2.9A,$ $V_{GEN} = -10V,$ $R_g = 1\Omega$
Turn-ON Rise Time 开启上升时间	t_r	-	12	18	ns	
Turn-OFF Delay Time 关断延迟时间	$t_{d(off)}$	-	33	50	ns	
Turn-OFF Fall Time 关断下降时间	t_f	-	9	18	ns	

[6] Pulse test; pulse width $\leq 300 \mu s$, duty cycle $\leq 2\%$. 脉冲测试：脉冲宽度 $\leq 300 \mu s$ ，占空比 $\leq 2\%$ 。

9. Typical Electrical Characteristics Curve 典型电特性曲线

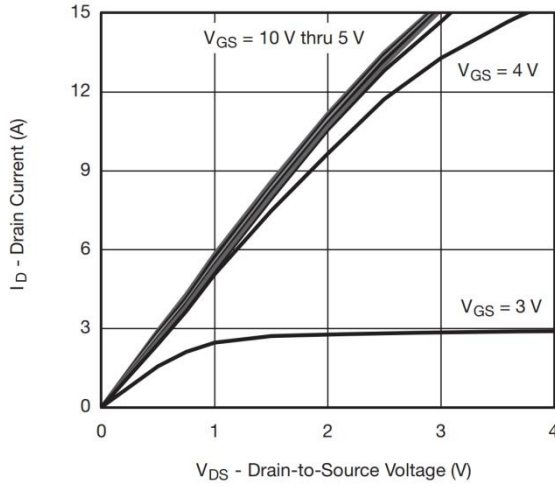


Figure1. Output Characteristics

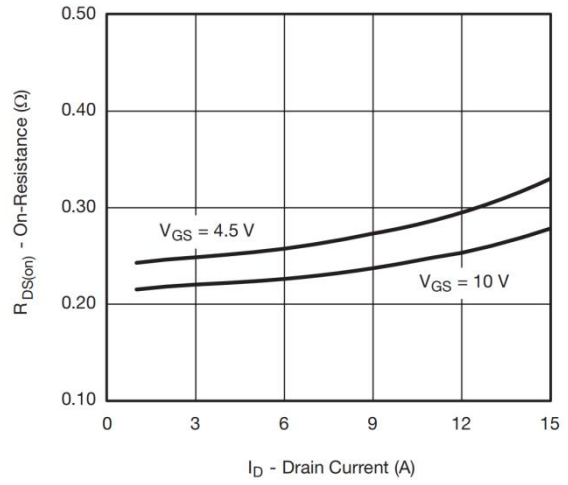


Figure2. On-Resistance vs. Drain Current

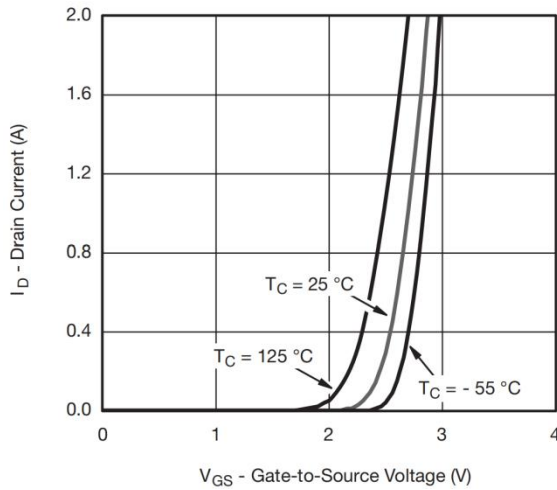


Figure3. Transfer Characteristics

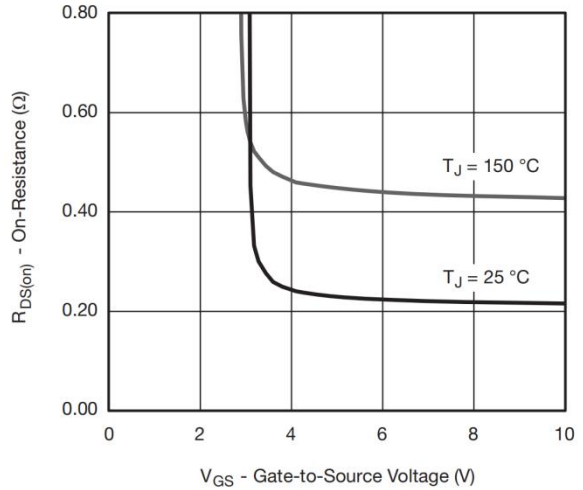


Figure 4. On-Resistance vs. Gate-to-Source Voltage

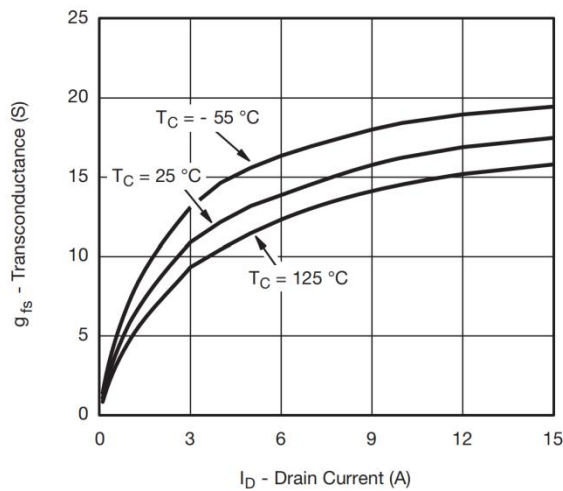


Figure 5. Transconductance

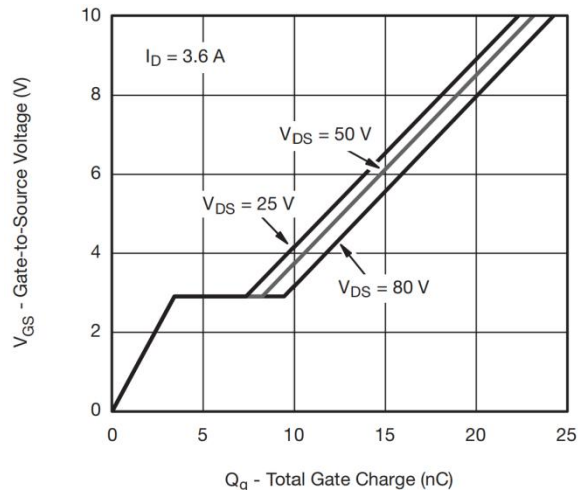


Figure 6. Gate Charge

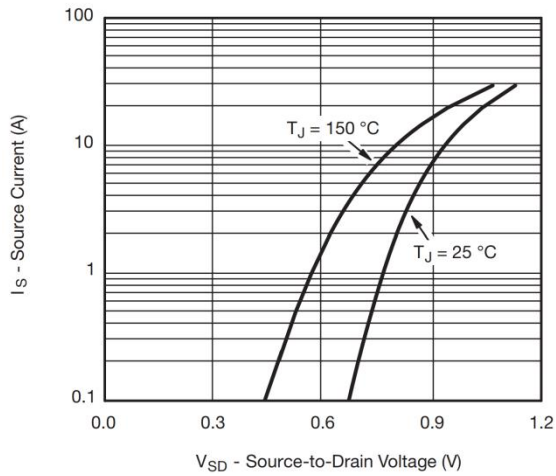


Figure 7. Source-Drain Diode Forward Voltage

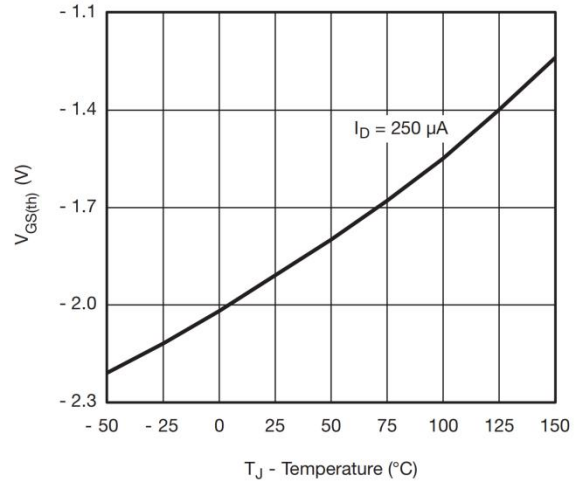


Figure 8. Threshold Voltage

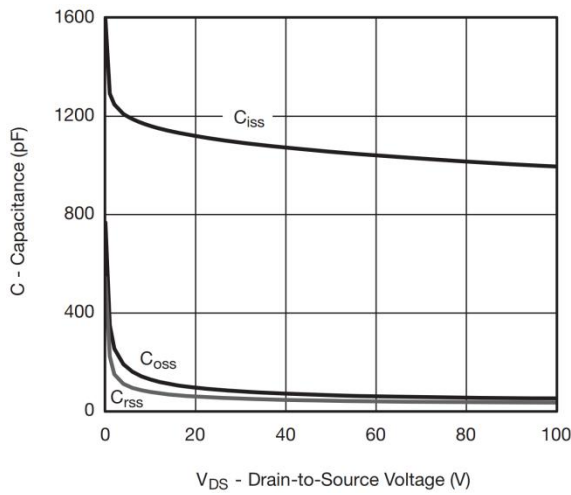


Figure 9. Capacitance

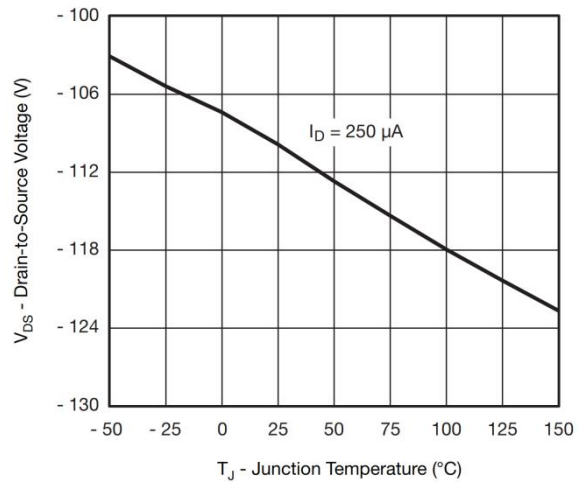


Figure 10. Drain Source Breakdown vs. Junction Temperature

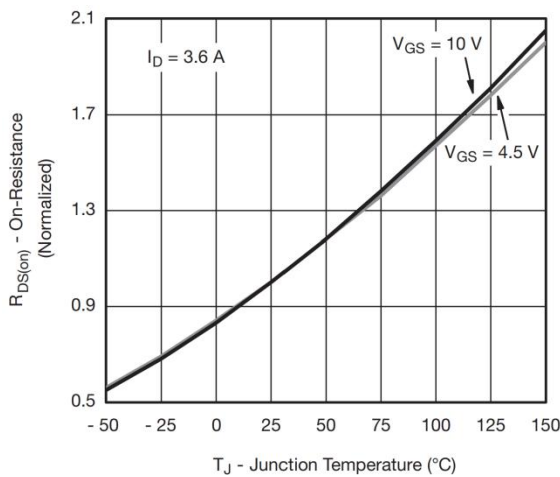


Figure 11. On-Resistance vs. Junction Temperature

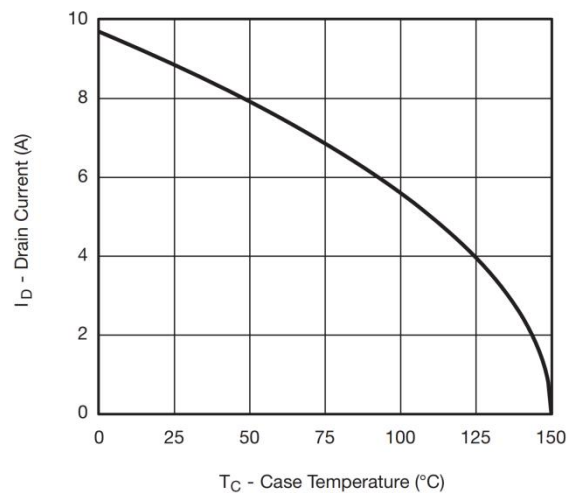


Figure 12. Current Derating

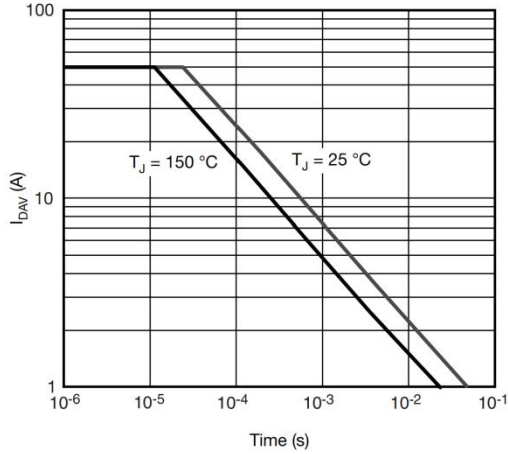
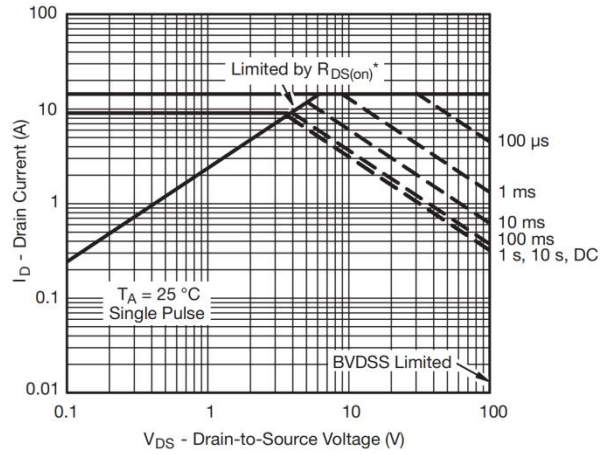


Figure 13. Single Pulse Avalanche Current Capability vs. Time



* $V_{GS} >$ minimum V_{GS} at which $R_{DS(on)}$ is specified

Figure 14. Safe Operating Area

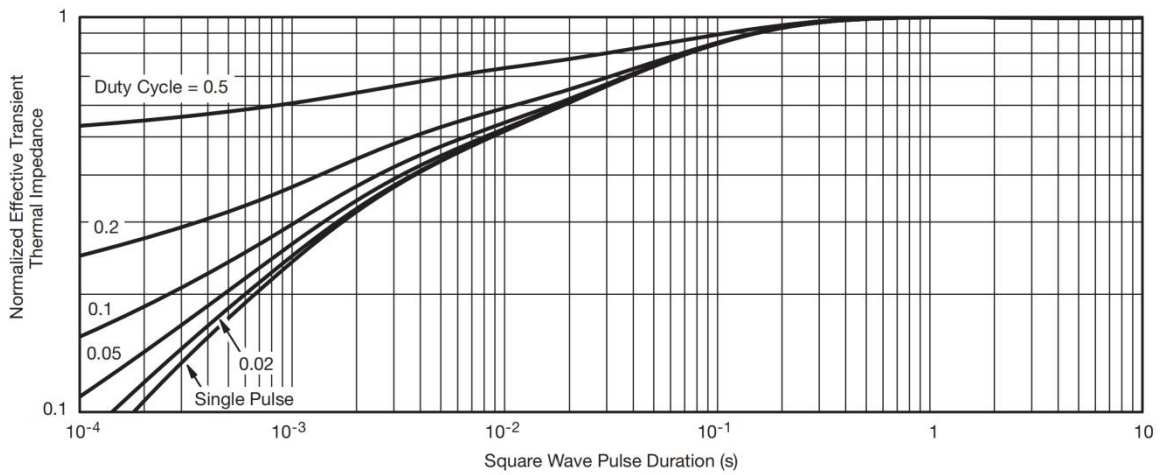
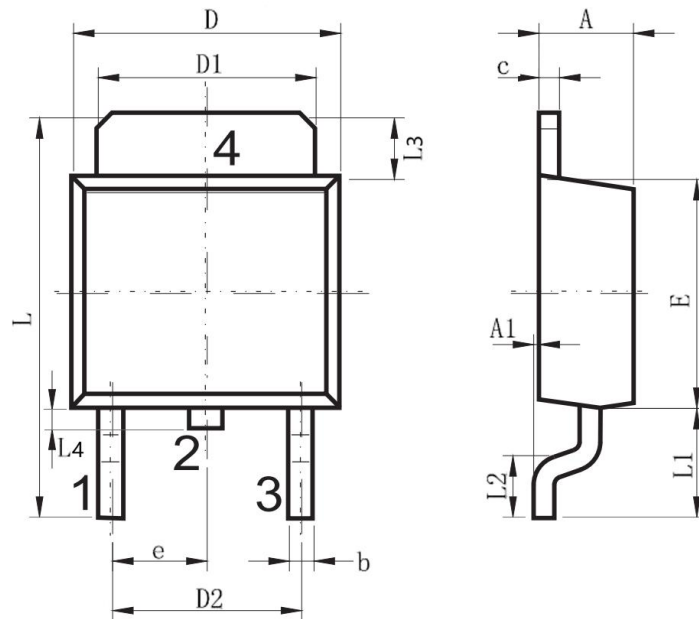


Figure 15. Normalized Thermal Transient Impedance, Junction-to-Case

10. Package Outline Dimensions 封装外形尺寸

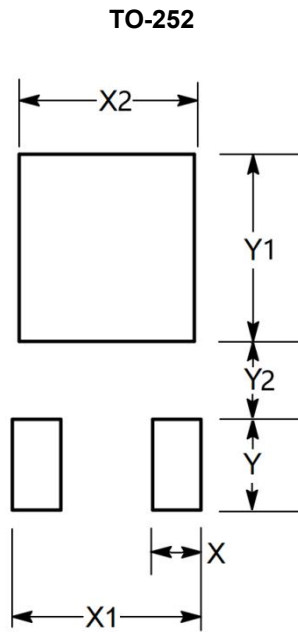
TO-252



Symbol 符号	Millimeters 毫米	
	Min.最小值	Max.最大值
A	2.10	2.50
A1	-	0.127
b	0.50	0.90
c	0.30	0.70
D	6.30	6.70
D1	5.10	5.50
D2	4.4	4.8
E	5.50	6.30
e	2.10	2.50
L	9.70	10.10
L1	2.70	3.10
L2	1.40	1.78
L3	1.20	1.60
L4	-	1.01



11. Suggested Pad Layout 推荐焊盘布局



Dimensions 尺寸	Millimeters 毫米
X	1.6
X1	6.17
X2	5.8
Y	3
Y1	6.2
Y2	2.58

Fig. Soldering footprint for TO-252

图 TO-252 的引脚焊接



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Date of release: 26 Dec 2025

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发布日期: 2025-12-26
